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LISTING OF CLAIMS

- 1.-26. (Cancelled)
- 27. (Currently Amended) A method of fabricating a micro-mirror structure[[s]] in a micro-mirror strip of micro-mirror structures comprising:

forming a pyramidal structure from a <u>first</u> substrate material; and

defining electrodes on the pyramidal structure <u>for positioning a mirror disposed adjacent</u>

to the pyramidal structure.

- 28. (Original) The method of claim 27, wherein forming the pyramidal structure comprises: anisotropic etching the pyramidal structure to form steps of various depths in the structure.
- 29. (Original) The method of claim 27, wherein the electrodes include four electrodes and forming the electrodes further comprises arraigning each electrode on a different one of quadrants of the pyramidal structure.
- 30. (Original) The method of claim 28, wherein the steps are polygonal in shape.
- 31. (Currently Amended) The method of claim 27, wherein a second wafer substrate material is bonded to the first substrate material processed wafer.
- 32. (Currently Amended) The method of claim 31, wherein the <u>second substrate material</u> second wafer is a silicon-on-insulator wafer and is bonded to the <u>first substrate material</u> wafer with a device side facing the wafer.
- 33. (Currently Amended) The method of claim 31, further comprising:

disposing a material to define the a mirror in a surface of the second substrate material wafer.

- 34. (Currently Amended) The method of claim 31, further comprising:
 defining sensors in the surface of the second substrate material wafer.
- 35. (Currently Amended) The method of claim 27, further comprising:

 adding dam structures to at least one of the substrate materials wafers to isolate the structure from adjacent micro-mirror structures in a strip of micro-mirror structures.
- 36. (Currently Amended) The method of claim 34, further comprising:

 defining other electronic components of the micro-mirror structures in one or the other of
 the substrate materials wafers.
- 37. (Withdrawn) A hinge comprising:

a plurality of parallel hinge sections provided by vertical slots therein, the slots and parallel hinge sections being dimensioned to provide vertical and lateral stiffness to and a minimal torsion spring constant for the hinge.

38. (Original) A micro-mirror assembly comprising:

a frame:

an array of two-dimensional deflecting mirrors mounted in the frame; and
dams disposed between the mirrors to block viscous interaction between each of the two
dimensional deflecting mirrors and adjacent ones of the two-dimensional mirrors.